

L Number	Hits	Search Text	DB	Time stamp
1	156	card\$1 same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adhesive glue\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 11:58
2	23	(card\$1 same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adhesive glue\$1)) and 235/\$7.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 11:46
3	133	(card\$1 same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adhesive glue\$1)) not ((card\$1 same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adhesive glue\$1)) and 235/\$7.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 11:46
4	4230	card\$1 same antenna same (chip circuit ic module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 12:00
5	4074	(card\$1 same antenna same (chip circuit ic module) ) not (card\$1 same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adhesive glue\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 12:00
6	407	((card\$1 same antenna same (chip circuit ic module) ) not (card\$1 same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adhesive glue\$1))) and 235/\$7.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 12:00
7	45	((((card\$1 same antenna same (chip circuit ic module) ) not (card\$1 same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adhesive glue\$1))) and 235/\$7.ccls.) and etch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 12:01
8	16	(((((card\$1 same antenna same (chip circuit ic module) ) not (card\$1 same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adhesive glue\$1))) and 235/\$7.ccls.) and etch\$4) and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 12:02
9	6	((card\$1 same antenna same (chip circuit ic module) ) not (card\$1 same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adhesive glue\$1))) same etch\$4 same resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 12:04